

APPLICATION DATA SHEET

Electronic Version 0.0.11

Stylesheet Version: 1.0

Attorney Docket Number: 9223-US-PA

Publication Filing Type: new-utility

Application Type: utility

Title of Invention: FLIP-CHIP PACKAGE SUBSTRATE AND FLIP CHIP DIE

Customer Number Attorney: 31561



Customer Number Correspondence Address: 31561



Foreign Priority:

91208321 TW 2002-06-05 Priority Claimed

INVENTOR(s):

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FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

Patent fees are subject to annual revisions on or about October 1st of each year.

Large Entity

TOTAL FEES AUTHORIZED: \$ 900

BANK (CREDIT) CARD INFORMATION:

Credit Card Number: 3109
Expiration Date: 20030430
Authorized Name: LEE, HUAI-LU
Billing Address: 99999

BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	101	\$ 740

Subtotal For Basic Filing Fee: \$ 740

EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 22	103	\$ 18	2	\$ 36
Independent Claims: 4	102	\$ 84	1	\$ 84

Subtotal For Extra Claims Fees: \$ 120

ADDITIONAL FEES

Fee Description	Number	Quantity	Fee Code	Amount	Fee Paid
Recording Each Patent Assignment Per Property Fee	00000000	1	581	\$ 40	\$ 40

Subtotal For Additional Fees: \$ 40